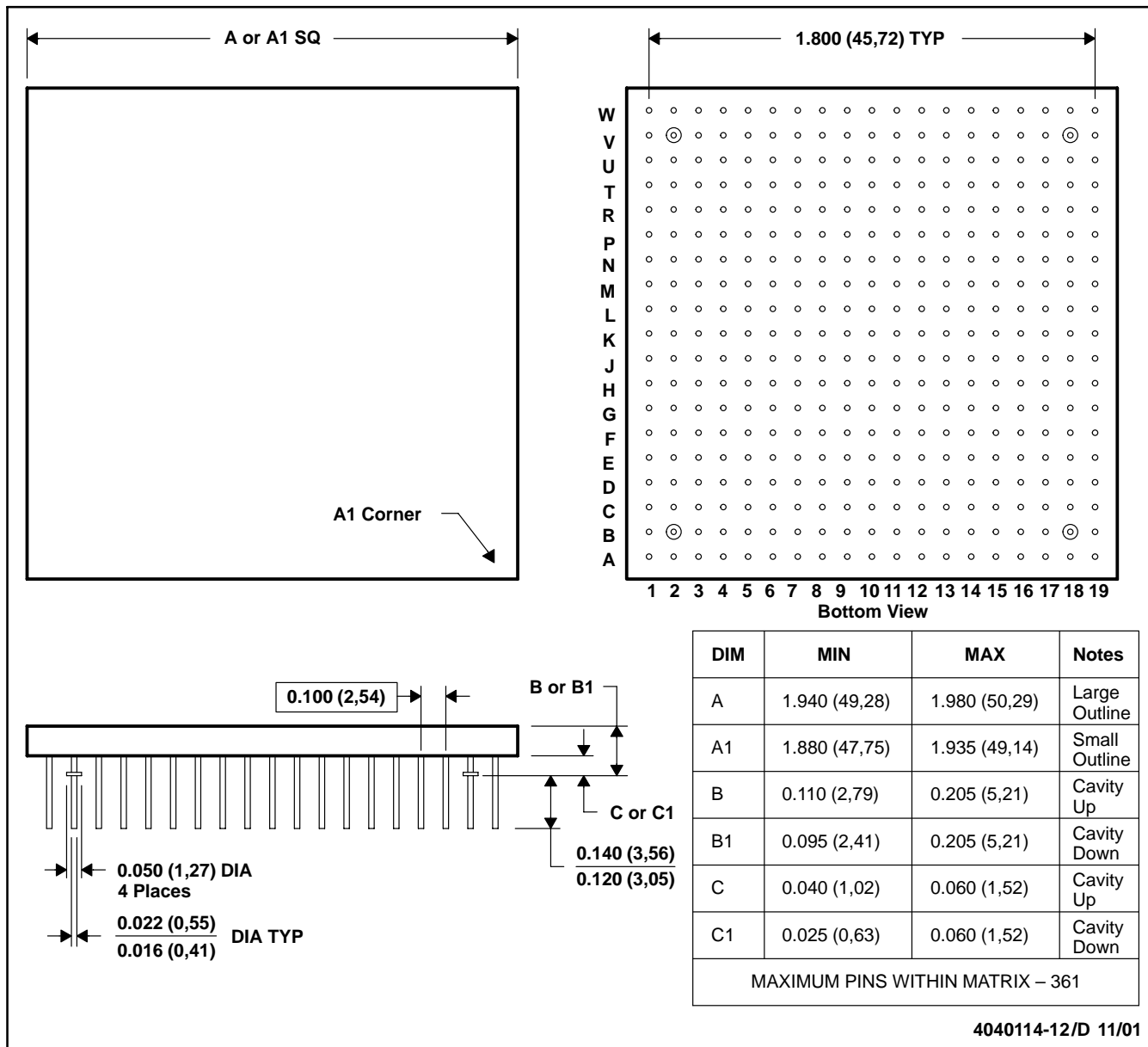


GB-GA (S-CPGA-P19 X 19)

CERAMIC PIN GRID ARRAY



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Index mark can appear on top or bottom, depending on package vendor.
 - D. Pins are located within 0.010 (0,25) diameter of true position relative to each other at maximum material condition and within 0.030 (0,76) diameter relative to the edge of the ceramic.
 - E. This package can be hermetically sealed with metal lids or with ceramic lids using glass frit.
 - F. The pins can be gold-plated or solder-dipped.
 - G. Falls within MIL-STD-1835 CMGA11-PN and CMGA23-PN, and JEDEC MO-067AL and MO-066AL, respectively

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